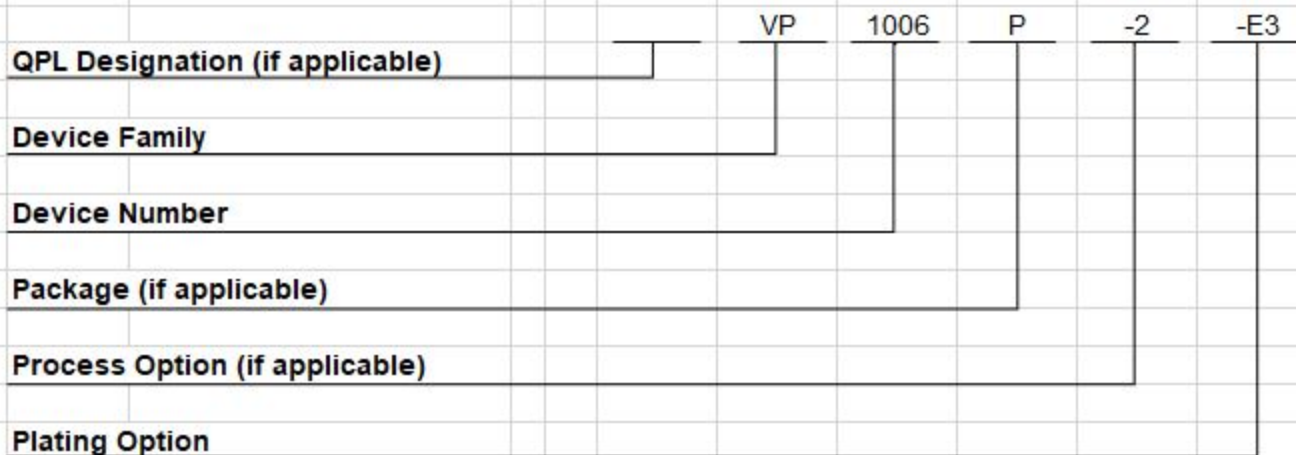


Small Signal Discrete



Device Family

Package

P ----- Hermetic Dual-In-Line Sidebrazed Package

CR - N-Channel Current Regulator

DPAD - Dual JFET Low Leakage Diode

J - TO-226AA (TO-92) Cased JFET

JPAD - TO-226AA (TO-92) Cased JFET Low Leakage Diode

PAD - Metal Can Cased JFET Low Leakage Diode

PN - TO-226AA (TO-92) Cased JFET

SST - Surface Mount Device

U - Metal Can Cased JFET

V - Low Power MOSFET (Special)

VCR - N-Channel Voltage Controlled Resistor

VN - N-Channel Low Power MOSFET

VP - P-Channel Low Power MOSFET

VQ - Quad (4 devices/package) Low Power MOSFET

2N - JEDEC Registered Device

3N - JEDEC Registered Device

Process Option

-2 ----- JANTXV Equivalent Flow, Group A QCI only

Plating Option

-E1 ----- Tin/Lead (Sn/Pb) Termination

-E3 ----- 100% Tin (Sn) Termination. RoHS Compliant

-G3 ----- Gold (Au) Termination. RoHS Compliant

QPL Designation

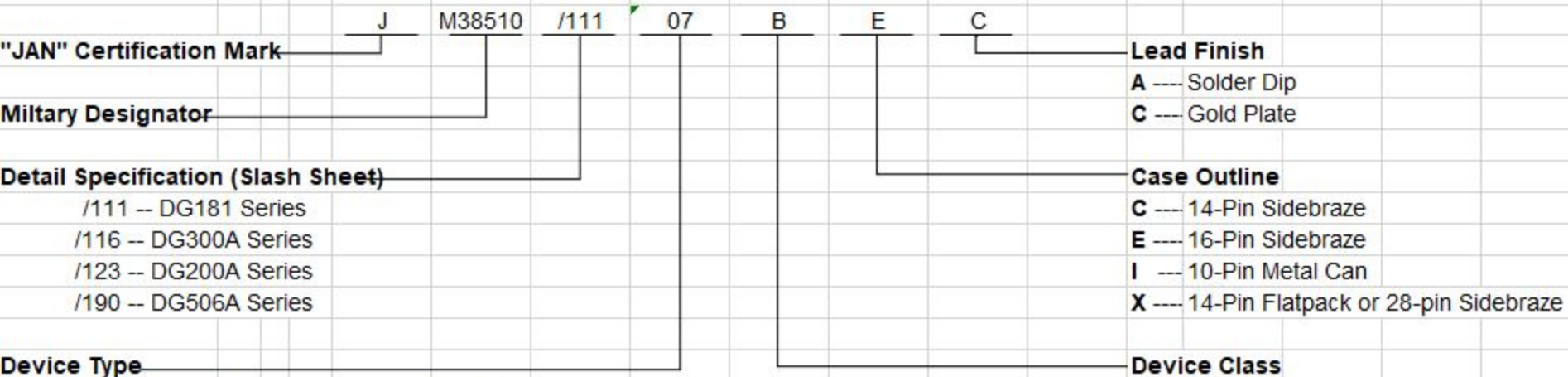
JAN - Lowest Quality Level per Mil-Prf-19500

JANTX - Mid Non-Space Quality Level per Mil-Prf-19500

JANTXV - Highest Non-Space Quality Level per Mil-Prf-19500

JANS - Space Quality Level per Mil-Prf-19500

MIL-M-38510



Detail Specification (Slash Sheet)

- /111 -- DG181 Series
- /116 -- DG300A Series
- /123 -- DG200A Series
- /190 -- DG506A Series

Lead Finish

- A --- Solder Dip
- C --- Gold Plate

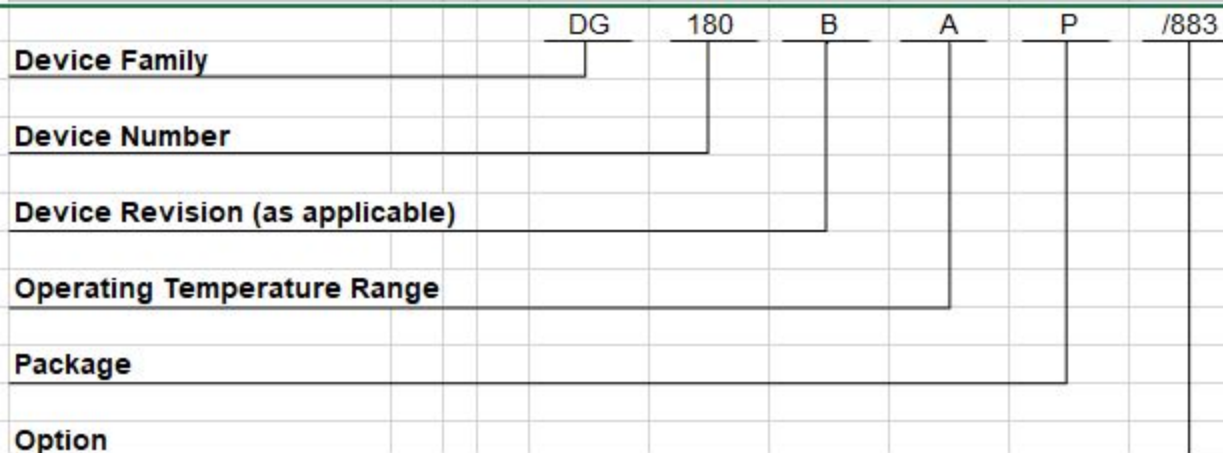
Case Outline

- C --- 14-Pin Sidebrazed
- E --- 16-Pin Sidebrazed
- I --- 10-Pin Metal Can
- X --- 14-Pin Flatpack or 28-pin Sidebrazed

Device Type	01 -	02 -	03 -	04 -	05 -	06 -	07 -	08 -
/111	DG181	DG182	DG184	DG185	DG187	DG188	DG190	DG191
/116	DG300A	DG301A	DG302A	DG303A	DG304A	DG305A	DG306A	DG307A
/123	DG200A	DG201A						
/190	DG506A	DG507A	DG508A	DG509A				



Integrated Circuits



Device Family

(1 or 2 Letters)

DG - Analog Switch and Analog Multiplexer

Device Number

(3 or 4 Digit Numbers)

Operating Temperature Range

(1 Letter)

A --- -55 to +125°C

B --- -25 to +85°C

C --- 0 to +70°C

D --- -40 to +85°C

E --- -40 to +105°C

Package

A ----- Metal Can

J ----- Dual-In-Line Package ---- Plastic

K ----- Dual-In-Line Package ---- Ceramic DIP

L ----- Flat Pack

M ----- CerQuad J-leaded Chip Carrier

N ----- Plastic J-leaded Chip Carrier

P ----- Dual-In-Line Package ---- Sidebrazed

Q ----- TSSOP

R ----- Dual-In-Line Package ---- Sidebrazed

W ----- Wide Body SOIC

Y ----- Narrow Body SOIC

Z ----- LCC

Option

/883 ---- Processed to the current revision of Mil-STD-883, Level . Compliant Non-JAN

-4 ----- Ruggedized plastic flow

-T1 ---- Tape-and-Reel